Product Lineup

Thermalnite®

▶Thermalnite®

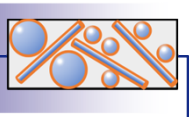
Features: Fiber length D50 approx.14 μm
Fiber Diameter D50 approx.3.2 μm
Applications: Thermal interface sheets, encapsulants, adhesives, gap fillers, thermoplastics

▶Thermalnite® Powder

Features: Fiber length D50 approx.10 μm
Fiber Diameter D50 approx.2.7 μm
Applications: Grease, adhesives, underfill

※ Surface treatment is also available for the above products.

Hybrid Filler



▶Hybrid Filler – Small Particles

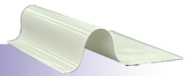
Features: Short Thermalnite fibers +spherical AlN, max particle size: 80 μm
Applications: Encapsulants, adhesives, grease, gap fillers, thermoplastics

▶Hybrid Filler – Large Particles

Features: Short Thermalnite fibers +spherical AlN, max particle size: 300 μm
Applications: Gap fillers, encapsulants, thermoplastics

※ Surface and water-resistant treatment is also available for the above products.

Thermal Interface Sheets



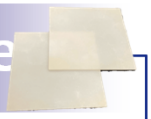
▶Low Thermal Resistance Sheets

Thickness: 0.1, 0.2, 0.5, 1.0 mm
Sizes: A4, A5
Target Devices: Controllers, power supplies, optical transceivers, SSDs, LEDs, LDs, etc.

▶High Thermal Conductivity Sheets

Thickness: 0.5, 1.0 mm
Target Devices: Power modules, motor drive units, communication module ICs, CPUs, etc.

Ceramic Substrate



▶High-Strength AlN Substrates (In-Plane Oriented)

Thermal Conductivity: 170, 200, 230 W/m·K (under development)
Thickness: 0.2–1 mm
Size: □4.5inch
Applications: Power modules, LED/LD modules, etc.

U-MAP Co., Ltd.
Ultimate Material and Processing

Please Contact us here ▶